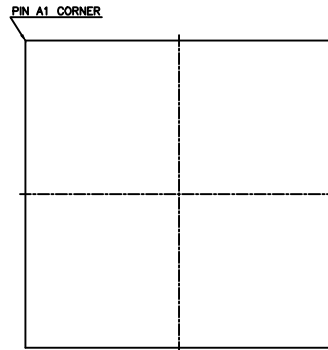
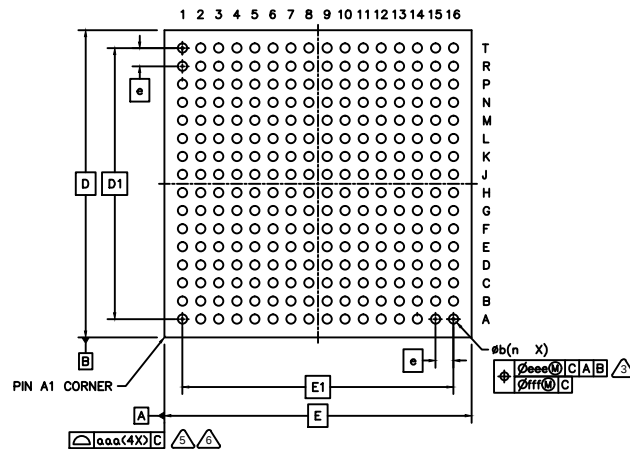
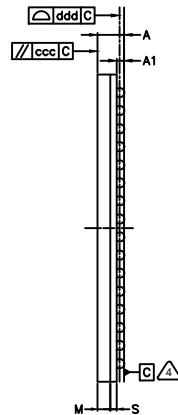




TOP VIEW



SIDE VIEW



BOTTOM VIEW

	Symbol	Common Dimensions		
		MIN.	NOM.	MAX.
Body Size:	X E		17.000	
	Y D		17.000	
Ball Pitch:	e		1.000	
Total Thickness:	A	1.400	1.460	1.540
Mold Cap Thickness:	M		0.700	Ref.
Substrate Thickness:	S		0.360	Ref.
Ball Diameter:			0.500	
Stand Off:	A1	0.300	0.400	0.500
Ball Width:	b	0.450	0.500	0.550
Package Edge Tolerance:	aaa		0.200	
Mold Parallelism:	ccc		0.200	
Coplanarity:	ddd		0.200	
Ball Offset (Package):	eee		0.250	
Ball Offset (Ball):	fff		0.100	
Ball Count:	n		256	
Edge Ball Center to Center:	X E1		15.000	
	Y D1		15.000	

NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\square$.
- PRIMARY DATUM $\square$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
- JEDEC REFERENCE: JEP95 DR4.14

Title: Package Outline Drawing	Pkg Type: CABGA	Document No: POD-250079	
Product Family: LFMXO4/LFMXO4D	Pin Count: 256		
Product Name: LFMXO4-015/025/050-BFG256 LFMXO4D-040/050-BFG256	Pkg Size: 17x17 mm	Rev: C	PAGE: 3/3

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